SPECIFICATION

(Reference sheet)

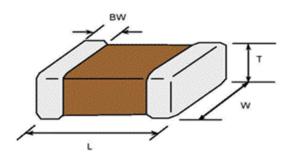
- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

- · Samsung P/N : · Description :
- CL10C100CB8NNNC CAP, 10pF, 50V, ± 0.25pF, C0G, 0603

A. Samsung Part Number

| | | CL ① | <u>10</u> ② | <u>C</u> 3 | <u>100</u> ④ | <u>C</u> 5 | <u>B</u> 6 | <mark>8</mark> ⑦ | <u>N</u> 8 | <u>N</u> 9 | <u>N</u> 10 | <u>C</u> 10 |
|-----------|----------------------------|------------------------------------|----------------|---------------|--------------------------------|---------------|----------------|---------------------|---------------|---------------|----------------|--|
| - | Series Size | Samsung Multi-lay 0603 (inch co | | erami | | | ± 0.10 | mm | | | W: | 0.80 ± 0.10 mm |
| 3 4 | Dielectric Capacitance | C0G 10 ⊳F | | | Inner electrode Termination | | | | Ni Cu | | | |
| († (5) | Capacitance tolerance | ± 0.25 pF | | | | (9) | Platin | ng | ,,,, | | | Sn 100% (Pb Free) Normal |
| 6) 7 | Rated Voltage Thickness | 50 V 0.80 ± 0.10 mm | | | | 0 10 11 | Speci Packa | ial | | | | Reserved for future use Cardboard Type, 7" reel |

B. Structure and dimension



| Samsung P/N | Dimension(mm) | | | | | | | | |
|-----------------|---------------|-------------|-------------|-------------|--|--|--|--|--|
| (Lead Free) | L | W | Т | BW | | | | | |
| CL10C100CB8NNNC | 1.60 ± 0.10 | 0.80 ± 0.10 | 0.80 ± 0.10 | 0.30 ± 0.20 | | | | | |





C. Samsung Reliability Test and Judgement condition

| | Performance | Test condition | | | | |
|-------------------|--|--|--|--|--|--|
| Capacitance | Within specified tolerance | 1Mb±10% 0.5~5Vrms | | | | |
| Q | 600 min | | | | | |
| Insulation | 10,000Mohm or 500Mohm× <i>μ</i> F | Rated Voltage 60~120 sec. | | | | |
| Resistance | Whichever is smaller | | | | | |
| Appearance | No abnormal exterior appearance | Microscope ('10) | | | | |
| Withstanding | No dielectric breakdown or | 300% of the rated voltage | | | | |
| Voltage | mechanical breakdown | | | | | |
| Temperature | C0G | | | | | |
| Characteristics | (From -55℃ to 125℃, Capacitance change s | should be within ±30PPM/℃) | | | | |
| Adhesive Strength | No peeling shall be occur on the | 500g×F, for 10±1 sec. | | | | |
| of Termination | terminal electrode | | | | | |
| Bending Strength | Capacitance change : | Bending to the limit (1mm) | | | | |
| | within $\pm 5\%$ or $\pm 0.5 \text{ pF}$ whichever is larger | with 1.0mm/sec. | | | | |
| Solderability | More than 75% of terminal surface | SnAg3.0Cu0.5 solder | | | | |
| | is to be soldered newly | 245±5℃, 3±0.3sec. | | | | |
| | | (preheating : 80~120 $^\circ C$ for 10~30sec.) | | | | |
| | | | | | | |
| Resistance to | Capacitance change : | Solder pot : 270±5℃, 10±1sec. | | | | |
| Soldering heat | within $\pm 2.5\%$ or ± 0.25 pF whichever is larger | | | | | |
| | Tan δ, IR : initial spec. | | | | | |
| Vibration Test | Capacitance change : | Amplitude : 1.5mm | | | | |
| | within $\pm 2.5\%$ or ± 0.25 pF whichever is larger | From 10Hz to 55Hz (return : 1min.) | | | | |
| | Tan δ, IR : initial spec. | 2hours ´ 3 direction (x, y, z) | | | | |
| Moisture | Capacitance change : | With rated voltage | | | | |
| Resistance | within $\pm 7.5\%$ or ± 0.75 pF whichever is larger | 40±2℃, 90~95%RH, 500+12/-0hrs | | | | |
| | Q : 133.33 min | | | | | |
| | IR : 500Mohm or 25Mohm × μF | | | | | |
| | Whichever is smaller | | | | | |
| High Temperature | Capacitance change : | With 200% of the rated voltage | | | | |
| Resistance | within $\pm 3\%$ or $\pm 0.3 \text{ pF}$ whichever is larger | Max. operating temperature | | | | |
| | Q: 300 min | 1000+48/-0hrs | | | | |
| | IR : 1,000Mohm or 50Mohm × μF | | | | | |
| | Whichever is smaller | | | | | |
| Temperature | Capacitance change : | 1 cycle condition | | | | |
| Cycling | within $\pm 2.5\%$ or ± 0.25 pF whichever is larger | Min. operating temperature $\rightarrow 25^{\circ}$ | | | | |
| | Tan δ , IR : initial spec. | \rightarrow Max. operating temperature \rightarrow 25 °C | | | | |
| | , | | | | | |
| | | | | | | |
| | | 5 cycle test | | | | |

* The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5°C, 10sec. Max)

A Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.

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The products listed in this Specification sheet are **NOT** designed and manufactured for any use and applications set forth below.

Please note that any misuse of the products deviating from products specifications or information provided in this Spec sheet may cause serious property damages or personal injury. We will **NOT** be liable for any damages resulting from any misuse of the products, specifically including using the products for high reliability applications as listed below.

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- *①* Aerospace/Aviation equipment
- 2 Automotive or Transportation equipment (vehicles, trains, ships, etc)
- 3 Medical equipment
- (4) Military equipment
- 5 Disaster prevention/crime prevention equipment
- Ø Power plant control equipment
- ⑦ Atomic energy-related equipment
- Indersea equipment
- Itraffic signal equipment
- Data-processing equipment
- ① Electric heating apparatus, burning equipment
- ② Safety equipment
- 13 Any other applications with the same as or similar complexity or reliability to the applications